XIDyn collaboration

a new approach to high-energy 2D detection for 4th generation synchrotrons

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1. European Synchrotron Radiation Facility





Science and Technology Facilities Council

Future Detectors for the European XFEL. Sep 18 – 19, 2023

Outline

1. Introduction

- Motivation
- DynamiX and XIDER projects
- XIDyn collaboration

2. Front-end architecture

- Readout concept
- Continuous and pulsed illumination
- Data handling and telegram protocol

3. Experimental results

- Prototypes and characterisation
- High-flux CZT

4. XIDyn collaboration

- Common MPW design
- Scale-up plans



Motivation

New generation (4th) of synchrotron and FEL facilities

- Diamond II
 - Planned upgrade
- ESRF Extremely Brilliant Source (EBS)
 - In user mode since 2020

New science opportunities require improved instrumentation

- X-ray detectors
 - Extended dynamic range
 - Shorter time domains: intrinsic time resolution and frame rate
 - Detection of high energy photons





DynamiX and XIDER projects



"Low energy" single-crystal diffraction

- "Soft" organic samples (e.g. protein crystals)
- Energy range: 15 to 30 keV
- Data accuracy is a must (crystal structure determination)
- "Long" integration times: ~10 μs to (many) ms
- Frame rate determined by integration time



"High-energy" time resolved diffraction

- "Hard" inorganic samples (often polycrystalline)
- Energy range: 30 to 100 keV
- Sensitivity to fast changes is crucial
- Sub-µs repetition (limited by beam time structure)
- Continuous and burst mode readout (memory)



Different target applications and parameter space!

XIDyn collaboration

Common technical choices

- Readout concept
- High-flux CZT
- Data Acquisition Framework

XIDyn collaboration

- Started in 2022
- Development of a common platform
- Attempt to merge both designs

Front-end concept



High-flux CZT (Redlen & Due2Lab)





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Readout Concept

Common "pixel" requirements

- Pixel size: 100 µm
- Conceived for high-Z sensors \rightarrow Cd(Zn)Te
- High dynamic range:
 - Single photon sensitivity
 - Up to ~ 10^9 photons/s/pixel (or above if possible)
- Operation with "continuous" and "pulsed" beams
- Nearly 100% duty-cycle operation should be possible

Focus on XIDER architecture

Similar considerations for DynamiX

Example of Diamond II fill pattern



Example of ESRF-EBS fill patterns





Readout Concept

Continuous conversion front-end with one stage

- Charge-sensitive amplifier (CSA) collects charge
- Charge pump removes well-defined charge packets (eq. to n photons) from the input node
 - Single photon sensitivity
 - Infinite dynamic range (ultimately limited by counter depth)
 - Pumping must be fast enough to handle the photon rate
 - Mostly insensitive to CSA saturation
- Data output is digital







Readout Concept

Continuous conversion front-end with two stages (pipeline)

- First stage (coarse) \rightarrow high dynamic range
- Second stage (fine) \rightarrow single photon (or sub-photon) resolution
- Transfer stage in between





Readout implementation discussed in: *J. Inst.* **16** P03023 <u>https://doi.org/10.1088/1748-0221/16/03/P03023</u>





Flexible front-end to cope with both modes

Continuous illumination



Incremental digital integration discussed in: J. Inst. **15** C01040 https://doi.org/10.1088/1748-0221/15/01/C01040

Standard integration

• Leakage accumulated

Digital Integration

- Integration
- Digitization
- Accumulation



Pulsed illumination

Features

- Fast front-end (rise time ~10-20 ns)
- 192×16 bit RAM storage per pixel
- Dynamic range limited by charge pump frequency
- Major limitation: reset and transfer time

Example for XFEL

- f_{burst}: 1 MHz
- f_{cp}: 200 MHz
- N_{ph}: 8 ph
- DR: 8×200MHz/1 MHz ~ 1600 ph

Dynamic range can be easily adapted with bigger packet size





On chip data handling



Frame 0 Frame 1 Frame 2 Image: Storage Command Store at address 102 Discard Add to address 10 Telegram Readout Command Read from address 2 Read from address 67 No Readout

Telegram concept discussed in "Concepts for the Data Flow Control on the XIDer Readout ASIC" D. Schimansky, conference record ULITIMA 2022, under publication

Custom-designed telegram protocol

- Maximum flexibility in data taking
- Sends commands to the ASIC channels on frame-level for data storage and readout
- Allows for event-by event decisions, like triggering or data rejection.



Telegram protocol storage mode examples



• There are many more modes

• Actual choice depends on the user's requirements

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Prototypes



ASIC design

The XIDER pixel functionality is particularly **complex**

- ✓ Fast analog front-end
- In-pixel analog-to-digital conversion
- Digital logic, sequencer, multiple modes of operation
- ✓ Built-in memory
- × Power hungry

The pixel design has progressed incrementally

- Six chips (T1 to T6) designed so far
- Not all the chips have used for X-ray testing
- Last X-ray measurements with T4: investigation at the pixel level
- T7 is planned

More info on T6&T7 in the last section

ASIC T4: 4×4 pixels





TSMC CMOS 65nm

Prototypes

Prototypes T4

- CdTe-ohmic (Acrorad) or CZT (Due2Lab & Redlen)
 - 1 mm thick CdTe (ohmic contacts)
 - 2 mm thick high-flux CZT
- 4×4 matrices of 100 or 200 µm pitch
- TSMC CMOS 65nm technology (version T4)
- Interconnection by Polymer Assembly Technology

Characterization

- The initial investigation work was done with CdTe assemblies
- CdTe devices perform poorly
 - Instability and irreproducibility of dark/leakage current
- High-flux CZT assemblies available only very recently
- Measurements taken both with 30 keV X-rays at BM05/ESRF and with LED sources at the lab







Calibration

Parameters to be calibrated Front-end 10: CP₀: 456 ADU Front-end 09: BL1: 220.26 ADU ENC1: 4.16 ADU r.m.s S1 S2 300 1.0 Threshold --- Erf fitting --- CP size Data Cf2 50f Cf1 50f 250 Data 0.8 Injection 500 motors S3 C3 400f IN A1 A2 0.6 from sensor Equivalent p Cadd 900f 0.4 Vth2 Vth1 々 0.2 S1..3 50 full custom 0.0 synthesized 0 · Sequencer 230 180 190 200 210 220 240 250 260 200 600 0 400 800 1000 10 bit CNT 8 bit CNT DAC:COMP1 [ADU] DAC:CP0Ibias [ADU] other FE cell ---- ShiftReg ShiftReg → SER OUT

Threshold calibration

Charge packet calibration

Parameters to be calibrated

- Thresholds and charge pumps $(\times 2)$ •
- All trimmable with 10-bit DACs •
- Using internal (or external) charge injection •



Characterisation

Example of calibrated channel



- Internal injection circuit
- Coarse stage counts in packet of 8 photons
- Fine stage in packets of 1 photon
- Mid-tread response
- Electronic noise: 350 e⁻ rms



Dynamic range vs charge pump frequency

- External injection circuit
- Dynamic range can be extended with charge pump frequency
- Dynamic range already approaching 0.7×10⁹ ph/s/pixel

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Time-resolved capabilities



- XIDER active subframe of ~100 ns
- 4-bunch filling mode: 100 ps X-ray pulses every 704 ns
- Photon induced signal

Example of 4-bunch full orbit scan

Delay between XIDer subframe and bunch arrival [μs]







Afterglow/aftersignal

- Extra-charge delivered by the sensor after end of irradiation
 - CdTe performs much worse than CZT
 - Residual still present in HF-CZT
- For XFEL pulsed operation \rightarrow effect mitigated



High-flux CZT

"High-flux" CZT

- Better charge transport properties than CdTe
- High-flux version improves hole transport properties

Redlen Technologies

- Redlen does not supply prototypes, slowly opening to the synchrotron market
- Their sensor processing technology (e.g. pixelation) is still somewhat "rudimentary"

Collaborating with IMEM-CNR-Due2Lab (Parma):

- IMEM reprocesses "high-flux" CZT sensors from Redlen
- Developed a suitable platinum contact technology
 - First devices by the end of 2022 with very promising results:
 - Low leakage current (significantly lower than CdTe)
 - In terms of time stability (reduced polarization effects)
 - Good linearity up to high X-ray flux densities









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Common MPW design



MPW ASIC

- DynamiX: 16×16 pixel
- XIDER: 16×16 + STFC serialiser
- 14 Gbps high-speed data serializers
- Pitch is continuous (110 µm)
- One piece of CZT over the device

Chip is alive

New ASIC/sensor prototypes under assembly



T7

Full reticle scale-up plans

- "STFC Detector Hub" funding scale up to full reticle over next 18 months
- Merging design: add adjustable gains/cancellations to match ESRF and Diamond needs
- Performance optimisation
 - Power, timing distribution
- Aim for adjustable number of serialisers. For example
 - 8 for high rate \rightarrow 100kHz readout \$\$\$
 - 1 for low rate \rightarrow 10kHz readout \$
- Use RAM to sum and keep flux capability or sum sequence of frames, rolling buffer, veto, compare...
- Interested in other collaborators, requirements... this version and future ones













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Thank you for your attention